



Copper Molybdenum Heatsink

- Lightweight thermal management requirements
 - Microwave carriers and heatsinks
 - Microelectronic package bases
- Controlled coefficient of thermal expansion
- Good thermal and electrical properties
- Near-net shape capability with Polese's patented powder metallurgical process

PROPERTY DATA

Composition	± 2 wt. %	85 Mo, 15Cu
Density	g/cc	10.0
Thermal Conductivity	W/m K	150
Thermal Expansion	25°C - 300°C	7.0 x 10⁻⁶
Electrical Conductivity	%IACS	25
Young's Modulus	GPa	274
Thermal Capacity	J/cc °C	2.76

Typical data is believed to be accurate and reliable, but is presented without guarantee or warranty.

Experienced materials and microelectronics packaging professionals are available to support material selection and design efforts. Contact your local representative or the factory today, or visit our web site at <http://www.polese.com> for more information.

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